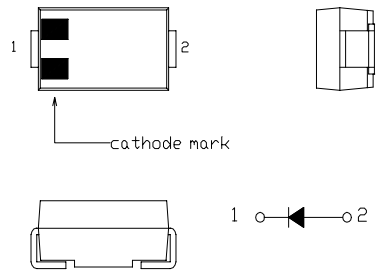
Nihon Inter Electronics Corporation

SBD Type : EC21QS10

FEATURES

* Miniature Size,Surface Mount Device
* Low Forward Voltage Drop
* Low Power Loss,High Efficiency
* High Surge Capability
* 30 Volts through 100Volts Types Available
* Packaged in 12mm Tape and Reel
* Not Rolling During Assembly

OUTLINE DRAWING



Approx Net Weight:0.06g

Maximum Ratings

Rating	Symbol	EC21QS10			Unit
Repetitive Peak Reverse Voltage	V_{RRM}	100			V
Average Rectified Output Current	I_o	1.3	Ta=25 ℃ *1	50Hz Half Sine Wave Resistive Load	A
		2.0	Tl=106 ℃		
RMS Forward Current	$I_{F(RMS)}$	3.14			A
Surge Forward Current	I_{FSM}	50	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T_{jw}	-40 to +150			℃
Storage Temperature Range	T_{stg}	-40 to +150			℃

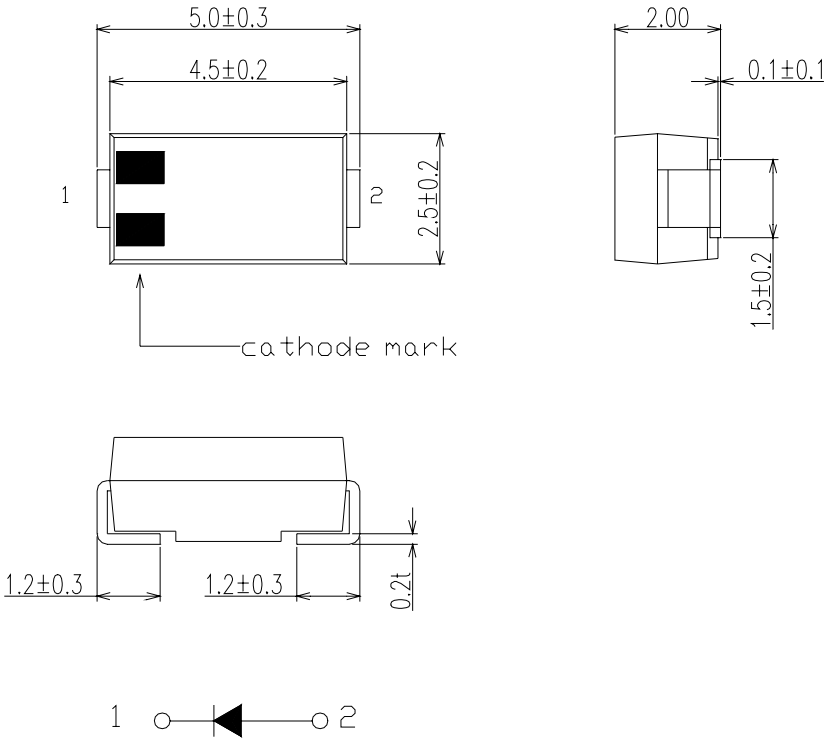
Electrical • Thermal Characteristics

Characteristics		Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current		I_{RM}	Tj= 25℃, V_{RM}= V_{RRM}	-	-	1	mA
Peak Forward Voltage		V_{FM}	Tj= 25℃, I_{FM}= 2.0A	-	-	0.85	V
Thermal Resistance	Junction to Ambient	$Rth_{(j-a)}$	Alumina Substrate Mounted *1	-	-	108	℃/W
	Junction to Lead	$Rth_{(j-l)}$	-	-	-	23	

*1 Alumina Substrate Mounted (Soldering Lands=2x2mm,Both Sides)
(Tl: Lead Temperature)

Nihon Inter Electronics Corporation

EC21QS10 OUTLINE DRAWING (Dimensions in mm)



soldering pad